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Technical Program

MONDAY, JUNE 8, 1998

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Co-chair: N. Camilleri, *AMD*

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TUESDAY, JUNE 9, 1998

10:30 am–11:50 am

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Session IX: MILLIMETER WAVE MMICS FOR RECEIVER APPLICATIONS

(Joint RFIC and IMS Session)

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(Joint RFIC and IMS Session)

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(Joint RFIC and IMS Session)

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Session XIII: MILLIMETER WAVE MMIC TECHNOLOGY

(Joint RFIC and IMS Session)

Chair: M. Kumar, *Lockheed Martin*

Co-chair: H.-C. Huang, *AMCOM Communications*

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Room 318/323

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(Joint RFIC and IMS Session)

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Co-chair: D. Lovelace, *Motorola*

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THURSDAY, JUNE 11, 1998

2:30 pm–5:00 pm

Camden Lobby

Interactive Forum

(Joint RFIC and IMS Session)

Chair: H. Newman, *Naval Research Laboratory*

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